

Material Declaration Report

Package Type:	TQFP 32L
Pericom Package Code:	FA32(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	143.000
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	3
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	8/5/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	78.092	OSE	Silica	60676-86-0	90.000	70.2831
			Epoxy resin	Proprietary	4.500	3.5142
			Phenol resin	Proprietary	4.000	3.1237
			Aromatic Phosphate	Proprietary	1.300	1.0152
			Carbon black	1333-86-4	0.200	0.1562
LEADFRAME	53.625		Copper (Cu)	7440-50-8	94.900	50.8901
			Nickel (Ni)	7440-02-0	3.200	1.7160
			Silicon (Si)	7440-21-3	0.720	0.3861
			Magnesium (Mg)	7439-95-4	0.180	0.0965
			Silver(Ag)	7440-22-4	1.000	0.5363
SILICON DIE	4.104		Silicon (Si)	7440-21-3	99.192	4.0709
			Non-hazardous Metal	Proprietary	0.808	0.0332
DIE ATTACH EPOXY	1.487		Silver	7440-22-4	76.000	1.1303
			Acrylic Resin	Proprietary	8.000	0.1190
			Polybutadiene derivative	Proprietary	5.500	0.0818
			Butadiene copolymer	Proprietary	1.000	0.0149
			Epoxy resin	Proprietary	2.500	0.0372
			Acrylate	Proprietary	5.500	0.0818
			Peroxide	Proprietary	0.500	0.0074
			Additive	Proprietary	1.000	0.0149
GOLD WIRE	3.117		Gold(Au)	7440-57-5	99.990	3.1171
			Impurities	-	0.010	0.0003
SOLDER PLATING	2.574		Tin (Sn)	7440-31-5	99.990	2.5737
			Impurity	-	0.010	0.0003

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.